

Energy Efficiency in Analogue and Mixed Signal Integrated Circuit Design

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Abstract: The Wireless communications field is one of the major successes of the engineering over the past two decades. The progress made in this area has not only produced a huge technological growth, but also a great impact at social and economic level. In fact, the possibility of being connected anywhere at any time has radically changed people character.

The evolution of wireless communications is obviously linked to the power consumption of devices, which also continues increasing due to the growing amount of data and transmission speed required by the new communication standards. This leads to an increasingly gap between power needs and battery capacity. Therefore, energy efficiency of electronics systems has become a crucial factor to maximize the lifetime of the available batteries and one of the most important research topics in integrated circuits design in recent years

Introduction:

The increase in power consumption is less dramatic for the digital domain, since it is partially compensated, as the technology scales-down, by the reduction of the supply voltage and the geometrical dimensions of a single device. The main reason for decreasing the supply voltage in modern CMOS technology is to avoid the possible breakdown of the transistors due to the extremely thin oxide. For a CMOS logic gate, e.g. an inverter, the simplest logic cell, the power consumption can be expressed as:

$$P = C_L \cdot V_{dd}^2 \cdot f \quad (1)$$

where C_L is the load capacitor at the output of the inverter, V_{dd} is the supply voltage and f is the operating frequency. Despite of the ever-increasing working speed, the power consumption in CMOS logic circuits is reduced as the supply voltage and geometry sizes scale down.

The System-On-Chip (SoC) trend is the main cause for the analogue and mixed-signal and digital integrated circuits (ICs) to be fabricated on the same wafer. This fact eventually requires the analogue and mixed-signal ICs to be fabricated in modern CMOS technologies to save cost. However, several challenges are encountered in the scaling-down of the CMOS technologies for analogue designs with not much clear advantages. The threshold voltage is not scaled as aggressively as the supply voltage to avoid leakage current in transistors. As a consequence, the available signal swing is lower and a reduction of the noise of the circuit to maintain the same dynamic range is required. Reducing thermal noise increases the power consumption of analogue and mixed-signal circuitry. Particularly, in discrete time applications, reducing circuit noise means increasing the capacitances which results in higher power consumption in order to maintain the same operation speed. Additionally, as technologies are scaled down, the output resistance of the MOS transistors decreases resulting in lower op-amp gain. In order to increase the gain, it is required to use either cascode transistors or cascade amplifiers, increasing the complexity of the circuits. These solutions worsen the swing problems and increase the power consumption.

The analogue-to-digital (A/D) converter is one of the most important and power consuming building blocks in modern electronics systems.

In portable bio-signals acquisition micro-systems, the power consumption requirements are taken to the extreme. For instance, medical implant devices, such as modern pacemakers, require extremely low power consumption (about 10-40 μ W) in order to operate up to 10 years or more using a small non-rechargeable battery. In wearable electronics for biomedical monitoring applications, extreme miniaturization is required and this will limit the battery size and power draw. Wearable electroencephalography (EEG) is a good example of such a power-limited system. EEG records the voltage between electrodes placed on the scalp and provides a non-invasive interface to the brain.

Another interesting arising application is the Energy Autonomous Sensors (EAS) which will represent a revolution in the use of wireless technologies, such as wireless sensor networks, in the ambient intelligence paradigms. Exploiting this continuously improving energy efficiency and advances in energy harvesting, miniaturized battery-less sensors that do not need to be recharged for their whole operational life are becoming possible nowadays.

1. Power reduction techniques in analogue integrated circuit design.

1.1. Biasing point optimization:

CMOS technology is used in most of the electronic devices because of its high density of integration. Traditional analysis of MOS circuits is often based on the assumption that every transistor is operating in the strong inversion region, although signal amplification can be done in any of the three inversion regions. The better knowledge of the strong inversion models and equations is one of the

main reasons for its use.

Although simple MOS amplifier stages have much higher bandwidths in the strong inversion region, parameters like voltage gain, power dissipation, white noise, and distortion can be optimized by operating in the weak or moderate inversion regions. Most often operation in weak inversion is synonymous to minimum power operation.

There are several advantages that make operating in weak inversion an interesting issue:

1. It is possible to achieve higher gains.
2. Low power consumption can be achieved as the quiescent drain current needed for this level of inversion is quite low.
3. Lower distortion compared to the strong inversion region.
4. Higher output resistance of the devices of the input stage due to the low drain currents of transistors operating in weak inversion region.

But there are also some disadvantages when designing in weak inversion region. The most important is the reduction in circuit bandwidth and therefore in frequency operation although, they can be maximized if some issues are taken into account. In a single transistor, the maximum operating frequency is determined by the gate capacitances, CGS and CGD. In order to maximize the device bandwidth, these capacitors need to be kept as small as possible which is achieved with minimum transistor width and length.

In order to improve MOS modeling techniques, a large amount of research has been done until this moment regarding transistor MOS operation at the three levels of inversion. All this research has been quite useful to define accurate equations for the weak inversion region, as for instance the EKV model.

Many analogue circuits have been designed using weak inversion region, such as operational trans conductance amplifiers, filters, ADCs, etc., all of them performing very low power consumption.

1.2. Digitally assisted techniques:

Recent CMOS technologies open an interesting possibility for ADC design by translating analogue precision problems to the digital domain, where higher frequency signals can be processed at much lower energy cost. The additional complexity of digital processing circuits can be compensated by relaxing the analogue requirements and, as a consequence, lowering the total required energy per conversion.

Digitally assisted techniques have become a major concern in ADC design nowadays. Some traditional A/D conversion architectures (such as Successive-Approximation-Register-based-SAR- and $\Sigma\Delta$ ADCs) can be considered digitally assisted architectures since they make extensive use of CMOS digital logic. On the one hand, oversampling is a widely implemented technique in $\Sigma\Delta$ converters with high energy efficiency. As modern technologies allow a more efficient digital data processing, there are trends to extend these techniques to other Nyquist ADC architectures to decrease the required energy per conversion. On the other hand, there are a great number of approaches based on compensating errors generated in the analogue parts (such as mismatch and offset of the comparators) by means of implementing redundancy-based architectures and digital calibration methods instead of very power-demanding analogue compensation techniques.

In next sections, some of the most interesting trends involving digitally assisted techniques will be explained.

1.2.1 calibration and redundancy:

As it was commented before, the analogue circuits suffer some difficulties due to the MOSFET size reduction. One of the most applied techniques to compensate these errors is to introduce some digital calibration schemes, usually employing redundancy-based ADC architectures.

As an example, a widely employed architecture in wireless communication systems to reach fast operation at very high frequencies is the Flash ADC. Traditionally, these schemes have been characterized by using very power-demanding topologies with multiple gain stages for offset compensation. Actually, there are different design trends, mainly based on "relaxed precision" comparators redundancy combined with digital error compensation of mismatch and offset deviations. A first approach is illustrated in , where a bank of comparators with a factor-four redundancy is implemented with no special care about their offset or mismatch properties, drastically decreasing the consumption in the analogue blocks. In an initial calibration phase, the most suitable comparator for every input range is selected and the rest are powered down, with no contribution to power consumption of the system. Another example is a Flash ADC using process variations to generate the input references from random comparators offsets whose resolution and input signal range are optimized by means of digital calibration.

A great variety of similar approaches combining redundancy and digital error correction methods can be implemented in a similar way. For instance, there are redundancy-based ADC with a current trimming DAC for error compensation to minimize the input-referred offset of the comparators or partially redundant schemes -with only some additional comparators- with background calibration implemented during conversion.

1.2.2. Time

interleaving:

Time-Interleaving (TI) technique is a method based on the concept of running a system with M parallel channels by taking just one sample alternatively from each one. As a consequence, the ADC as a block would operate at an M times higher frequency than each individual channel. This allows reaching higher operation frequencies at no additional cost of analogue power consumption. However, mismatch between channels (usually the most limiting factors are offset and gain mismatch and clock skew errors) will reduce the resolution of the system. It is possible to compensate these errors using digital calibration or post processing.

Where a 6-bit Time- interleaving ADC working at 1.25 GS/s without any off-line calibration, error correction or post processing has been designed. The proposed architecture has been implemented using a two time-interleaved SAR ADCs topology combined

with flash ADC sub-conversion processes, allowing a reduction from 65 to 6 comparators and lowering its power consumption well below typical values for state-of-art flash ADCs without digital calibration techniques. Another example of a Time-interleaving 7-bit SAR ADC working at 2.5 GHz is described on (Alpman et al., 2010). The proposed scheme is based on 16 parallel ADC running at 1.25GS/s with two additional ADC to allow background calibration to compensate offset and mismatch errors. Timing calibration can be done by means of adjusting a programmable delay line, which can be done during the packet header of the communication standard used for data transmission.

1.2.3. Time domain processing.

With the evolution of CMOS fabrication processes, higher bandwidth is available for analogue designers. Therefore, systems that process signals in the time domain can benefit of the improved speeds to achieve larger resolutions. Traditional time-based architectures, such as dual-slope converters, can achieve very high resolution at the cost of large conversion times. Nowadays, as technology scales down, such time-based architectures are not only limited to low speed applications. A good example of achieving high-energy efficiency using time-domain processing and an extensive use of digital logic is the ADC architecture presented in (Yang & Sharpshkar, 2006, 2007). They propose a current-mode ADC that works like a pipelined converter which performs the residue amplification and subtraction in time domain, without the use of conventional amplifiers. The ADC is made of only two matched capacitors, a comparator and a switched reference current source controlled by a digital state machine. Since only a single comparator and one reference current source are used for the entire conversion process, the ADC consumes minimal power and avoids inaccuracies due to gain errors and offsets.

In (Jimenez-Iratorza et al. 2013) an interesting Time-to-Digital converter (TDC) achieving high energy efficiency is presented. It implements a recursive successive approximation algorithm in the time domain to perform the conversion with a low-voltage fully digital circuitry and very low power consumption.

1.3 Analogue circuitry simplification:

In previous sections, the way of successfully translating most of the analogue complexity to the digital domain by applying some techniques has been discussed. Another complementary approach to improve power efficiency could be based on the design of simplified analogue sub-circuits, allowing higher speed operation and power consumption decrease in basic building blocks. These techniques would include not only system level designs strategies but also analogue basic topologies that can be applied to many different architectures. In this way, higher energy efficiency can be obtained also at SoC level.

In the next sections, a review of some of the most interesting approaches for circuitry simplification will be provided.

1.3.1 Switched OP-Amp and OP-Amp sharing.

Op-amps are usually one the most power-consuming basic analogue blocks; therefore, a feasible option to reduce power consumption is to minimize their number in designs. Many switched-capacitor circuits need an active op-amp only during one clock phase, the amplification phase. As a consequence, there are two widely used techniques to reduce the number of active op-amps (Kim et al, 2006); one shares op-amps between successive stages and the other switches them off during the sampling phase. Op-amp sharing is a technique based on using the op-amp for two adjacent stages in successive alternative phases. This technique is widely implemented in pipelined ADCs but can be applied to any op-amp based topology.

Two-stage Class-A switched-op-amp (SO) is the most popular solution for low power switched capacitor (SC) sigma-delta modulators with ultra-low supply voltage conditions. The SO saves about 30%-40% of the total power since its output stage is just turned off at the integrating phase. For instance, an application to implement a 4th order band-pass $\Sigma\Delta$ modulator using switched op-amps is presented in (Kuo & Liu, 2006). While a classic op- amp topology would require four integrators working in two phases, in the proposed architecture the $\Sigma\Delta$ modulator is implemented only with two switched op-amps, drastically reducing the power consumption. To further increase efficiency, class AB output and input stages can be used in the op-amp implementation. In (Wang et al., 2009) by turning off the entire SO together, instead of only the output stage, with its common mode feedback (CMFB) circuit, the power consumption of the SO can be reduced about 50%.

1.3.2. OP-Amp less.

The traditional way of designing analogue circuits relies on high gain op-amps in negative feedback loops. As it was stated before, the op-amp power consumption directly impacts in the overall system. Recently, there is the trend of replacing the op-amps by more power efficient blocks such as comparators, inverters or simple structures based on local feedback. In this section, some of these approaches are described to illustrate this trend.

CBSC (Comparator Based Switched Capacitors) and zero-crossing detector based circuits: The CBSC technique was firstly proposed in (Fiorenza et al., 2006) and is applicable to any traditional op-amp based SC circuit. This technique consists in replacing the op-amp by a comparator and one or more switched current sources. As the author explains, the power reduction relies in the fact that a CBSC circuit senses the virtual ground while in traditional op-amp based SC circuit the virtual ground is forced which is less energy efficient.

Several ADC prototypes have demonstrated the practical application of CBSS and its potential high energy efficiency. In a 10 bits pipelined ADC based in zero- crossing detector fabricated using 65nm CMOS technology is reported. Another pipelined zero-crossing detector based is presented in. It achieves 12 bits of ENOB sampling at 50MS/s with high power efficiency indicated by a FOM of 88fJ/step.

Inverter based $\Sigma\Delta$ Modulator: This technique is another approach in which the op-amp is replaced by a simple inverter, which can be considered as a very simplified amplifier architecture. In the past, inverters had been applied to SC circuits as low-performance amplifiers for micro power consumption (Hosticka, 1979). In spite of the limited performance of inverters compared with op-amps,

inverters attract attention again to be used in deep submicron technologies. This is because of their ability to operate with very low supply voltages. Recent works have demonstrated that inverter-based design techniques can be applicable to high-performance SC circuits in aggressively scaled CMOS technologies.

For example, present a hybrid $\Sigma\Delta$ modulator fabricated in 65nm CMOS technology. It uses a highly digitized architecture with a five bits quantizer and a digital filter in order to reduce the complexity of the feedback DAC. A first order analogue loop filter (implemented using inverters) reduces the analogue parts to the minimum, so the area and power consumption are drastically reduced. In (the inverter behaviour used as an extremely simple amplifier is explained in detail. Three discrete time (DT) $\Delta\Sigma$ modulators of second and third order completely implemented by means of inverters are presented in this work. All of them achieve high dynamic range under low voltage supply conditions with a power consumption that places the best of them in the state-of-the-art nowadays.

Simple analogue cells based in local feedback.: Simple local feedback can lead to substantial enhancement of the performance with low cost in terms of noise, area and power consumption as it is usually implemented by a simple structure.

One good example is the structure called the Flipped Voltage Follower (FVF), a popular building block that relies on the local feedback idea. It was proposed in (Carvajal et al., 2005) to improve the performance of the classical voltage follower by means of local feedback.

A very commonly implemented basic cell in analogue microelectronics is the voltage follower (Fig. 1a). However, the gate-to-source voltage (v_{GS}) of the transistor acting as the follower (M1) depends on the output current, which leads to a high distortion for large output current variations. Some solutions have been proposed to address this problem (Sánchez-Sinencio & Silva-Martínez, 2000), (Barthélemy & Kussener, 2001), (Carvajal et al., 2005). The FVF is the basic cell made up by transistors M1 and M2 and the current source I_B shown in Fig. 1b. The local feedback implemented by transistor M2 keeps constant the current through transistor M1; this decreases the output impedance increasing the linearity of the current copy and in spite of output current variations.

A modified version of the FVF was proposed in (Luján et al., 2013) showing a better performance for large excursions of the input signal up to 10MHz and allowing a reduction in the quiescent power consumption of about 15 times when comparing with the classical solution, for the same linearity performances.

The idea of using local feedback to maintain the linearity requirements, while the power consumption is decreased, can be extended to more complex systems such as ADCs. One example of this is the CT $\Sigma\Delta$ modulator described in the section 2.2 of this chapter. A low power extremely low area CT $\Sigma\Delta$ modulator implementation based on the FVF is explained.

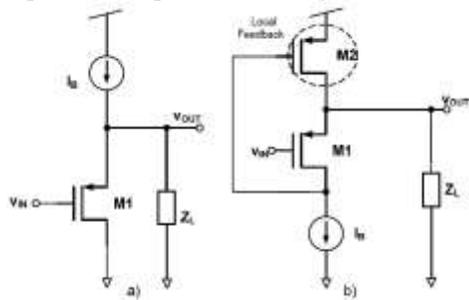


Fig. 1. Voltage followers: a) classical solution and b) FVF

Other op amp less approaches: Another example of a simplified op-amp-less architecture is the ADC array (Draxelmayer, 2004). Using parallelism to exploit the power efficiency of simple structures, a 6-bit ADC working at 600 MS/s based on eight SAR ADCs using a charge redistribution architecture is proposed. A power consumption of only 10 mW is obtained with very simple analogue circuitry (capacitors, switches and a comparator are sufficient) and no need for “precision” analogue blocks, like high gain op-amps In (Van der Plas, 2006) a 4-bit flash scheme with a comparator based simplified structure is proposed to design a high speed low-power ADC. Its structure is reduced to save power by removing all the non-essential blocks: Track & Hold, preamplifiers, reference ladder and bubble error correction. A comparator circuit combining sampling, amplification and reference level generation is used to implement the ADC obtaining a power consumption of only 2.5 mW.

1.4. Efficient use of biasing.

Charge transfer in class-A op-amp circuitry is inherently inefficient; the amplifier is biased with a constant current, while delivering on average only a small fraction of this current to the load. In this section, a more efficient use of biasing is discussed and various approaches adopted to solve this problem are commented

1.4.1 Dynamic and adaptive biasing:

In the last decades, several approaches have been proposed to optimize the efficient use of biasing towards the challenge of minimizing the power consumption-performance ratio. Most of them can be classified according to the concepts of dynamic and adaptive biasing. The term *dynamic biasing* was first coined in (Copeland & Rabaey, 1979), where a method to reduce the power consumption by taking advantage of having several clock phases in a SC integrator is proposed. This method is valid for all those circuits where there is a capacitive feedback between the output and a virtual ground Since then, the concept of dynamic

biasing has been extended, in general, to those approaches in which a block or part of it is connected or disconnected according to the received input power. An example of this technique is proposed in (Ozun et al., 2006) where a parallel combination of trans conductors is used, increasing the power consumption only if very low noise is required.

At the same time, the term of *adaptive biasing* (Degrauwe et al., 1981) has also become popular. It is usually referred to a continuous time change in the biasing according to the input. One of the most important adaptive biasing techniques is the class AB operation. In this technique, the slew rate limitation is tackled by boosting automatically dynamic tail currents for large inputs, keeping a well-controlled low quiescent current (Degrauwe et al., 1981), (Callewaert & Sansen, 1990), (Castello & Gray, 1985), (Tan & Chen, 2007), (Klinke et al., 1989), (Harjani et al., 1999). Several schemes can be found in the literature for class AB operation amplifiers. Most of them require of additional circuitry, which increases both power consumption and active area. Often they also imply additional parasitic capacitances to the internal nodes (Degrauwe et al., 1981), degrading the small signal performance of the circuit which is already poor due to the low quiescent current. In some cases, the stability issues get worse due to the use of positive feedback or structures that are sensitive to variations in process and environmental parameters (Callewaert & Sansen, 1990), (Klinke et al., 1989). Although other contributions consider negative feedback (Harjani et al., 1999), the required additional amplifiers to implement the feedback loops lead to complex designs. Another weakness of the tail current boosting topologies is that usually are not suitable for low voltage applications as in (Castello & Gray, 1985) due to the stacking of gate to source voltages.

Recently, some topologies based in the FVF (López-Martín et al., 2011) or using “Quasi” Floating Gate (QFG) techniques have been proposed (Ramírez-Angulo et al., 2008), while the first one offers simplicity of design and suitability for low-voltage operation simultaneously to high efficiency; the second one also minimizes the additional circuitry required just substituting a normal MOS transistor by a QFG MOS. Class AB operation can be applied to the input, to the output or both. This last option is known as superclass AB operation (López-Martín et al., 2005). The concept of class AB operation is so spread that today we can talk, for instance, about Class AB DACs (Seo et al., 2011), Sample & Holds (Sawigun & Serdjin, 2013) and multipliers (Sawigun & Serdjin, 2009) among others.

1.4.2 Assisted Op-Amp and helper techniques.

Instead of removing op-amps, as it has been explained in section 1.3.2, a less aggressive technique consists in keeping the op-amp but adding helper circuits that increase the energy efficiency by relaxing the requirements for the op-amp gain or bandwidth. For instance, in (Musah et al. 2007) the concept of correlated level shifting (CLS) is introduced. Correlated double sampling (CDS) technique can be used to reduce the error caused by finite open-loop gain, but it limits the maximum speed and its performance is poor near the rails. This makes it unsuitable for low voltage conditions, since the voltage swing is reduced too much. CLS is a SC technique similar to CDS, which also decreases the errors due to finite open-loop gain and allows rail-to-rail operation increasing the “distortion-free” swing. A third clock phase is needed but the settling time is about the same, so it does not have impact on the circuit speed. Open-loop gain requirements can be relaxed for a given resolution, leading to power consumption saving.

2. Applications examples.

In this section, one examples of design which make use of some of the previous power reduction techniques are presented. Then, the design of an efficient op- amp less implementation for CT $\Sigma\Delta$ modulators is described. In the proposed implementation, the op- amp is replaced by the compact local feedback structure explained in previous section.

2.1 Compact op-amp less CT $\Sigma\Delta$ modulator implementation for passive RFID application.

Combining sensors with passive RFID tags opens the way for new applications such as automotive and healthcare. As the passive RFID sensor nodes are intended to be powered by energy scavenging, ultra-low power consumption and robustness against process variations and changes in the supply voltage are essential requirements. In addition, low area occupancy is crucial in order to decrease the fabrication costs.

Low-bandwidth, moderate-resolution ADCs consuming a few microwatts are key elements for the sensor interface. Successive approximation register (SAR) converters are the typical choice for moderate-resolution low-frequency applications with ultra-low power requirements such as passive RFID. This type of converter achieves moderate resolution with very low power consumption and sets the state-of-the art in terms of energy efficiency. However, they consume large active area as the required DAC is normally implemented by a capacitor network. In this work the CT $\Sigma\Delta$ modulator architecture is proposed as an alternative to SAR architecture when the application also requires from very low area occupancy. CT $\Sigma\Delta$ modulators have become very popular over the last years, especially for lower power applications.

Traditionally, the loop filter is implemented either using an active-RC integrator or a gm-C approach. As it has been explained in the section 2 of this chapter, recent trends in low- power ADC design replace the internal op-amps (which usually are the most power consuming building blocks) with simple analogue circuitry. Following this trend, in this work a novel CT $\Sigma\Delta$ modulator implementation based on a local feedback is presented. The feedback provides a virtual ground node for reference subtraction without the need of op- amps or Operational Trans conductance Amplifiers (OTAs). A first-order $\Sigma\Delta$ modulator prototype with low complexity at system level and minimum area occupancy has been designed in order to validate the idea.

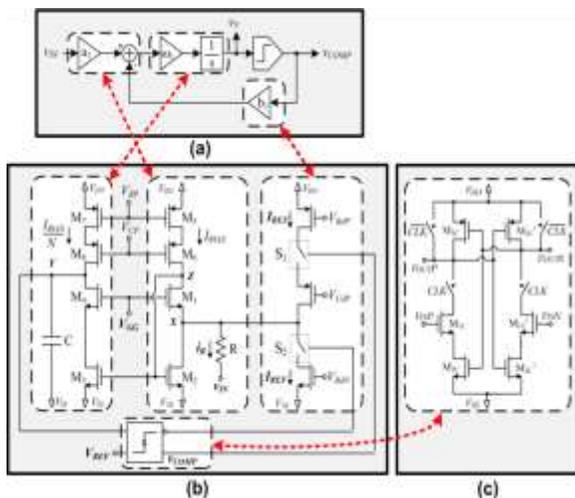


Fig. 2. First-order CT single-bit $\Sigma\Delta$ modulator. (a) Block diagram, (b) Proposed implementation, (c) Comparator schematic.

In Fig .2a the block diagram of a typical first-order CT single-bit $\Sigma\Delta$ modulator is shown. The modulator is made up of a comparator and a CT loop filter, which performs the subtraction and integration, as expressed in equation (1).

$$V_y(s) = (w_1 a_1 v_{in}(s) - b_1 v_{comp}(s)) / s \quad (2)$$

The compact implementation shown in Fig 2.b is proposed, where the input stage, the integrator stage and the feedback DAC have been highlighted.

The input voltage, v_{in} is converted into a current i_R by means of resistor R which connects the input signal to node X . Thanks to the feedback loop built up with transistors $M1$ and $M2$ and current source I_{BIAS} , the equivalent resistance at node X is extremely low.

In order to close the $\Sigma\Delta$ feedback loop the comparator controls two switches, $S1$ and $S2$, so that a reference current I_{REF} is injected or subtracted at node X depending on the comparator output. Therefore, the subtraction between the input signal and the comparator output is performed at node X in current mode. Note that both functions, the input voltage-to-current conversion and the feedback signal subtraction, are carried out by one resistor, two transistors and a current source. Then, the resulting current is copied and integrated in a capacitor. By a proper selection of V_{GG} , so that the quiescent value of the input voltage (V_{in}^Q) is equal to the bias voltage of node X (V_{X}^Q), the drain current of transistor $M2$ is given by.

$$I_{D,M2} = I_{BIAS} + (V_{in} + V_{in}^Q - V_{X}^Q) / R \pm I_{REF} / R \\ = I_{BIAS} + V_{in} / R \pm I_{REF} \quad (3)$$

As the input voltage is converted to current by a linear resistor, having a very low impedance at node X is crucial to achieve a good linearity at the input stage. This requirement is achieved thanks to the local feedback that keeps constant the current through transistor $M1$ in spite of output current variations at node X . Neglecting the body effect, the input impedance at node X is given by (Carvajal et al., 2005)

$$r_x = 1 / g_{m1} g_{m2} r_{o1}$$

which, for typical parameter values in the selected technology, is low enough to guarantee the linearity requirements for this application.

The current at the drain of $M2$, $i_{D,M2}$, is copied to node Y by the current mirror implemented with transistors $M3$ and $M4$, where the current I_{BIAS} is removed. The resulting current is injected into capacitor C where the integration is carried out. Finally, the voltage at node Y is given by (in the s-Domain):

$$V_y(s) = V_{in}(s) / R_{cs} \pm I_{REF} / CS \quad (4)$$

Expressions (2) and (4) are equivalent if $a_1 \omega_1 = 1/RC$ and $b_1 \omega_1 V_{COMP} = I_{REF}/C$. Note that no additional circuitry is required to bias the node Y . To reduce power consumption, the current through $M3$ (and $M7$) can be downscaled by modifying the gain of the current mirror. In our implementation a ratio of $N=3$ was chosen.

To save power, the dynamic latch-type comparator show in Fig .2c has been selected to close the modulator loop. Two switches open the latch branches during the reset phase so that the quiescent current consumption is zero.

To verify the proper operation of the proposed implementation, a first-order CT $\Sigma\Delta$ modulator prototype has been fabricated. The modulator digitalizes the signal coming from a MEMS accelerometer, which is a single-ended structure presently available in a 0.35 μ m CMOS technology. The ADC will be integrated in the same die with the MEMS accelerometer so it was designed in the same technology and with a single-ended input. The whole system is intended to be powered by an UHF RFID front-end which

provides a 3V nominal supply voltage typical for the selected technology (Vaz et al., 2010). Fig. 8a shows a microphotograph of the fabricated prototype. The total area consumption (without pads) is only 110µm x 125µm for the whole proposed circuit which makes it, to the author’s knowledge, the smallest ΣΔ modulator published for this range of specifications.

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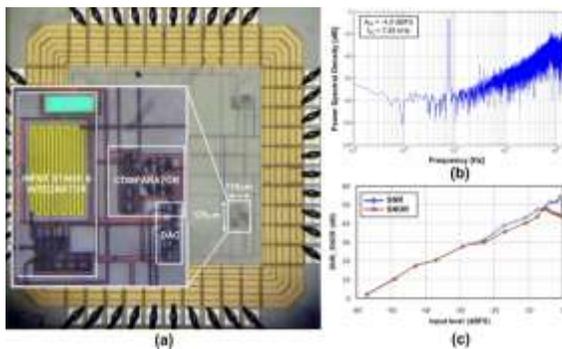


Fig. 3. (a) Circuit microphotograph, (b) Measured output spectrum, (c) SNR/SNDR versus input signal amplitude. Input signal frequency = 7.85 kHz. VDD = 3V.

The designed modulator has also shown to be very robust against supply voltage and bias current variations. The DR remains over 52dB for a supply voltage variation in the range 2.25 to 5 volts even for a 50% decrease of nominal bias current.

The FOM defined by (5) has been used to have an estimation of the energy efficiency achieved by the proposed ΣΔ modulator implementation. The minimum power consumption (4.35µW) was measured for a 2.25V supply voltage, leading to a FOM of 0.267 pJ/step. This value places this work close to the most power efficient CT ΣΔ modulators recently published, despite that it has been implemented in a reasonable old technology.

$$FOM = P / (2^{ENOB} \cdot 2BW) \quad (5)$$

Fig. 4a gives a graphical representation of the state of the art of power efficient ADCs in the same range of bandwidth. The measured performance of the proposed implementation is competitive in terms of energy efficiency compared with the state-of-the-art. The SAR converter (Harpe et al., 2010) sets the state-of-the-art and only a few ΣΔ modulators perform better than the proposed in this work.

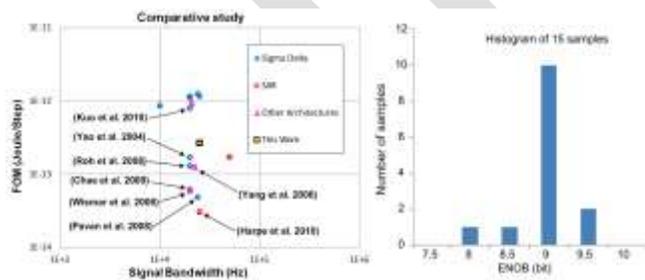


Fig. 4. (a) State of the art of ADCs regarding the selected FOM. (b) ENOB deviation for 15 measured samples (second version of the converter, VDD = 3V, input signal frequency = 7.85 kHz).

Fig. 4b shows a histogram of the ENOB deviation for 15 samples fabricated. Every sample worked properly with an ENOB variation lower than than ±0.5 bits, which is an indication of the robustness of the proposed modulator implementation against the process variation.

A compact implementation for CT ΣΔ modulators based on a local feedback has been presented. In order to validate the idea, a first order CT ΣΔ modulator for a self-powered sensor interface (9-bits of resolution and 25-kHz of signal bandwidth) has been designed in a 0.35µm CMOS technology. Experimental results confirm the idea and show that the proposed implementation leads to an extremely low area and highly power efficient ΣΔ modulator. The measured prototype has also shown to be very robust against process, supply voltage and bias current variations.

3. Conclusions.

In this chapter, the need of minimizing power consumption in electronic devices has been pointed out. For this reason, a review of the most common techniques used by IC designers with this purpose has been done. These techniques have been classified in four categories: biasing point optimization, digitally assisted techniques, analogue circuitry simplification and efficient use of biasing. In order to illustrate the large number of techniques that these categories involve, several references have been proposed through the chapter. Furthermore, one approaches based on the use of some of the reported technique have been described. The design proposes a compact op-amp less CT $\Sigma\Delta$ modulator for passive RFID applications. In order to reduce the power consumption, a local feedback technique is used.

REFERENCES:

- [1].Binkley, D. M.; Hopper, C. E.; Tucker, S. D.; Moss, B. C.; Rochelle, J. M. & Foty, D. P (2003).A CAD methodology for optimizing transistor current and sizing in analog CMOSdesign. *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems*, Vol. 22, No. 2, (February 2003), pp. (225–237).
- [2].Borkar, S. (1999). Design challenges of technology scaling. *IEEE Micro*, Vol.19, No.4, Jul-Aug 1999, pp. (23-29).Brooks, L. and Hae-Seung Lee; (2009). A 12b 50MS/s fully differential zero-crossing-based ADCwithout CMFB, *IEEE International Solid-State Circuits Conference - Digest of Technical Papers, ISSCC 2009*, (8-12 Feb. 2009), pp.(166 - 167).
- [3].Callewaert, L.G.A. & Sansen, W.M.C (1990). Class AB CMOS amplifiers with high efficiency, *IEEE Journal of Solid-State Circuits*. Vol. 25, No.3, (June 1990), pp. (684-691). ISSN 0018-9200.
- [4].Wang, H.; Xu, J. and Wu, X. (2009). A high power efficiency Class AB switched-opamp for low voltage low power sigma-delta modulators. *IEEE International Conference of Electron Devices and Solid-State Circuits, EDSSC 2009*. Vol. , No. (25-27 Dec. 2009).
- [5]Wisnar, U.; Wisland, D. & Andreani, P. (2006). A 0.2V 0.44 μ W 20 kHz Analog to Digital SD Modulator with 57 fJ/conversion FoM. *Proceedings of the 32nd European Solid-State Circuits Conference, 2006. ESSCIRC 2006*, (19-21 Sept. 2006).
- [6]Yang, H.Y.; Sarpeshkar, R. (2005). A time- based energy-efficient analog-to-digital converter, *IEEE Journal of Solid-State Circuits*, Vol.40, No.8, (Aug. 2005).
- [7].Yang, H.Y.; Sarpeshkar, R. (2006). A BioInspired Ultra-Energy-Efficient Analog-to-Digital Converter for Biomedical Applications. *IEEE Transactions on Circuits and Systems I:Regular Papers*, Vol.53, No.11, (Nov. 2006).
- [8].Yao, L.; Steyaert, M. & Sansen, W. (2006). *Low-Power Low-Voltage Sigma-Delta Modulators in Nanometer CMOS*. Springer. ISBN-13 978-1-4020-4139-6 (HB), The Netherlands.
- [9].Yeknami, A.F.; Qazi, F.; Dabrowski; J.J. and Alvandpour, A. (2010). *Design of OTAs for Ultra-Low-Power Sigma-Delta ADCs in Medical Applications*. *International Conference on Signals and Electronics Systems ICSES, Poland, September 2010*